

## Dual Hall Effect Latch with Speed & Direction Output

### 1 Product Description

The MT890X family is a Hall-effect dual latch produced by BCD technology with both high performance and high reliability. The Hall IC internally includes an on-chip Hall voltage generator, a voltage regulator for operation with supply voltage of 2.7V to 24V, temperature compensation circuitry, small-signal amplifier, Hall IC with dynamic offset cancellation system, Schmitt trigger and two open drain output, all in a single package.

Two Hall plates are integrated on the same chip, and using the high precision of the wafer fabrication process to ensure a fixed spacing of 1.45mm between the sensing elements. The first Hall plate provide the speed signal output. The combination of both the Hall plate signals is then internally processed to directly deliver a direction signal output.

The MT890X family provides SOT-23-6L for surface mount to customers & flat TO-94 for through-hole mount. All packages are RoHS compliant.

### 2 Features

- AEC-Q100 Automotive Qualified MT890XAT-SD & MT890XAT-SS
- Two Integrated Hall Plates for Direction Detection
- 2.7~24V Operating  $V_{DD}$  Range
- -40°C~150°C Operating Temperature
- Package Option:  
SOT-23-6L  
Flat TO-94
- Magnetic Sensitivity Option:  
MT8901 (BOP=25Gs, BRP=-25Gs)  
MT8902 (BOP=25Gs, BRP=-25Gs)
- Speed & Direction Open-Drain Output  
Dual Speed Open-Drain Output
- Self-diagnosis
- -30V Reversed Power Supply Protection
- Output Over Current Protection
- RoHS Compliant: (EU)2015/863

### 3 Product Overview of MT890X

Part No.	Description
MT890XAT-SS	SOT-23-6L, tape & reel (3000pcs/bag)
MT890XAT-SD	SOT-23-6L, tape & reel (3000pcs/bag)
MT890XA-SS	Flat TO-94, bulk packaging (500pcs/bag)
MT890XA-SD	Flat TO-94, bulk packaging (500pcs/bag)

Note:  
SS: SP1 + SP2  
SD: SP1 + DIR



### 4 Applications

- Windows Lifter with Anti-Pinch Feature
- Rotation Speed & Direction Detection
- Linear Speed & Direction Detection

### 5 Pin Configuration and Functions

SOT-23-6L	No.	Description
SP1	1	Speed Signal Out1
NC	2	Unconnected
SP2 or DIR	3	Speed Signal Out2 or Direction Signal Out
$V_{DD}$	4	Power Supply
GND	5	Ground
GND	6	Ground

Flat TO-94	No.	Description
$V_{DD}$	1	Power Supply
SP2 or DIR	2	Speed Signal Out2 or Direction Signal Out
SP1	3	Speed Signal Out1
GND	4	Ground

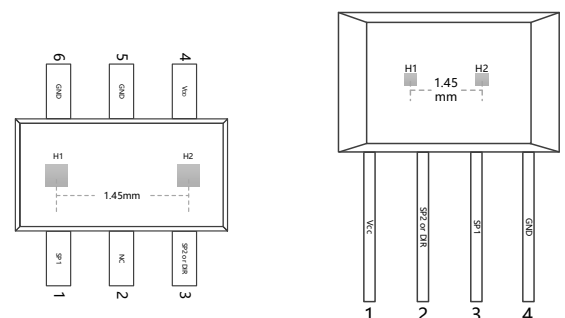


Figure.1 Pin Configuration & Functions  
SOT-23-6L & Flat TO-94 Top-View

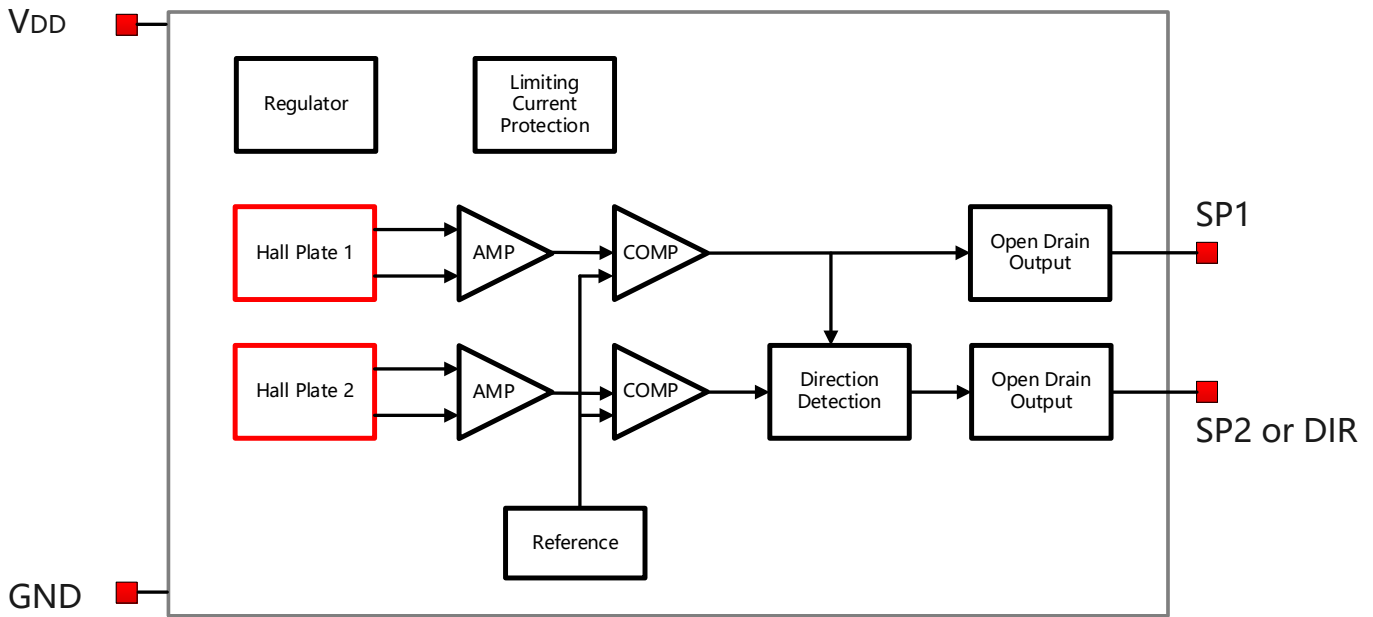
## Table of Contents

1	Product Description.....	1
2	Features.....	1
3	Product Overview of MT890X .....	1
4	Applications.....	1
5	Pin Configuration and Functions.....	1
6	Functional Block Diagram.....	3
7	Electrical and Magnetic Characteristics.....	3
	7.1 Absolute Maximum Ratings.....	3
	7.2 Electrical Specifications.....	4
	7.3 ESD Rating.....	4
	7.4 Magnetic Characteristics .....	5
	7.4.1 MT890X Series .....	5
	7.5 Characteristic Performance.....	5
8	Output Behavior vs. Magnetic Pole (SP1+ SP2 Mode).....	6
	8.1 Typical Output Waveform (SP1+ SP2 Mode).....	6
9	Output Behavior vs. Magnetic Pole (SP1 + DIR Mode).....	7
	9.1 MT8901-SD Typical Output Waveform (SP1 + DIR Mode).....	7
	9.2 MT8902-SD Typical Output Waveform (SP1 + DIR Mode).....	8
10	Typical Application Circuit.....	8
11	Self-diagnosis.....	9
12	Package Material Information.....	11
	11.1 SOT-23-6L Package Information.....	11
	11.2 Flat TO-94 Package Information.....	12
13	Copy Rights and Disclaimer.....	13

## Reversion History

1	Original Version	
2	Version 1.1	Update marking spec
3	Version 1.2	Update MT890XA Series Update the description of self-diagnosis
4	Version 1.3	Add characteristic performance
5	Version 1.4	Update AEC-Q100 Automotive of MT890XAT-SD & MT890XAT-SS
6	Version 1.5	Update MT8902 Series
7	Version 1.6	Update the packaging of MT890XA-SS & MT890XA-SD

## 6 Functional Block Diagram



**Figure.2** Functional Block Diagram

## 7 Electrical and Magnetic Characteristics

### 7.1 Absolute Maximum Ratings

Absolute maximum ratings are limited values to be applied individually, and beyond which the serviceability of the circuit may be impaired. Functional operability is not necessarily implied. Exposure to absolute maximum rating conditions for an extended period of time may affect device reliability.

Symbol	Parameters	Min	Max	Units
V <sub>DD</sub>	Supply Voltage	-	30	V
V <sub>RDD</sub>	Reverse Battery Voltage	-30	-	V
V <sub>OUT</sub>	Output Voltage	-0.7	30	V
I <sub>OUT</sub>	Continuous Output Current	-	40	mA
T <sub>A</sub>	Operating Ambient Temperature	-40	150	°C
T <sub>S</sub>	Storage Temperature	-50	160	°C
T <sub>J</sub>	Junction Temperature	-	165	°C
B	Magnetic Flux Density	No Limit		Gs

## 7.2 Electrical Specifications

At  $T_A = -40 \sim 150 \text{ }^\circ\text{C}$ ,  $V_{DD} = 2.7\text{V} \sim 24\text{V}$  (unless otherwise specified)

Symbol	Parameters	Test Condition	Min	Typ	Max	Unit
$V_{DD}$	Supply Voltage	Operating	2.7	-	24	V
$I_{DD}$	Supply Current	$F_s = 100\text{kHz}$	-	4.5	7.5	mA
$I_{OCP}$	Short Circuit Protection Current	$B > B_{OP}$ , $V_{OUT} = V_{DD}$	-	30	-	mA
$V_{DSON}$	Output Saturation Voltage	$I_{OUT} = 10\text{mA}$ , $B > B_{OP}$	-	-	0.4	V
$I_{OFF}$	Output Leakage Current	$V_{OUT} = 24\text{V}$ , $ B  <  B_{RP} $	-	-	10	$\mu\text{A}$
$T_R$ & $T_F$	Output Rise & Fall Time	$R_L = 1\text{K}\Omega$ , $C_L = 20\text{pF}$	-	-	1.0	$\mu\text{s}$
$T_{PO}^{(1)}$	Power on Time	$dV_{DD}/dt > 5\text{V}/\mu\text{s}$ $B > B_{OP(MAX)}$	-	20	30	$\mu\text{s}$
$F_s$	Sampling Frequency		-	100	-	KHz
$T_D$	Delay Time Refer to Figure.9&10		-	1.2	2.5	$\mu\text{s}$
$R_{TH}$	Thermal Resistance of SOT-23-6L		-	301	-	$^\circ\text{C}/\text{W}$
	Thermal Resistance of Flat TO-94			230		$^\circ\text{C}/\text{W}$

Notes:

(1) TPO here is defined when self-diagnosis is disabled. If self-diagnosis is enabled, please refer to the  $t_{edge3}$  in Part 11 (Self-diagnosis)

## 7.3 ESD Ratings

Symbol		Reference	Values	Unit
$V_{ESD}$	Human-body model (HBM)	AEC-Q100-002	Class H3	Grade
	Charged-device model (CDM)	AEC-Q100-011	Class C3	Grade

## 7.4 Magnetic Characteristics

At  $V_{DD}=2.7V\sim 24V$  (unless otherwise specified)

### 7.4.1 MT890X Series

Parameter	Symbol	Min	Typ	Max	Unit
Operating Point	BOP, $T_A = 25^\circ C$	10	25	40	Gs
Release Point	BRP, $T_A = 25^\circ C$	-40	-25	-10	Gs
Hysteresis Window	BHYST, $T_A = 25^\circ C$	20	50	80	Gs
Magnetic Matching	BOP1-BOP2 or BRP1-BRP2, $T_A = 25^\circ C$	-10		10	Gs
Magnetic Offset	BOP1+BRP1 or BOP2+BRP2, $T_A = 25^\circ C$	-10		10	Gs
Temperature Coefficient			-1000		ppm/ $^\circ C$
Hall Sensor Spacing			1.45		mm

## 7.5 Characteristic Performance

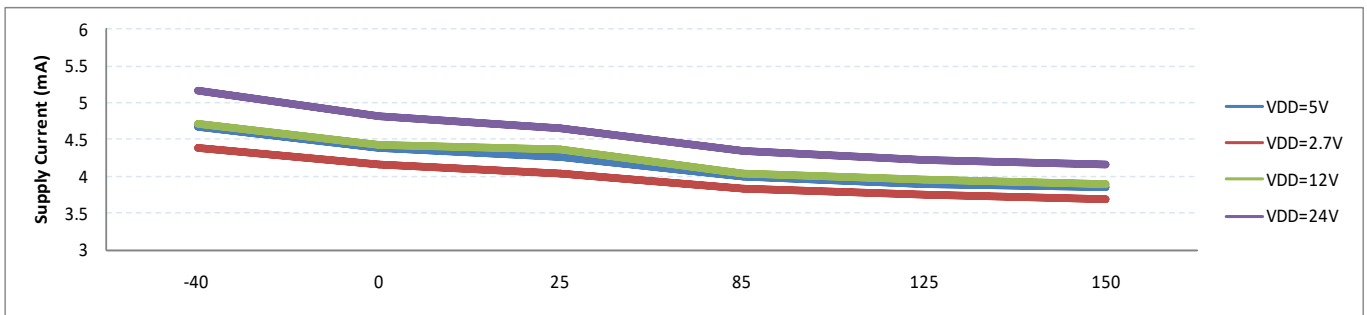


Figure.3 Supply Current vs. Temperature &  $V_{DD}$

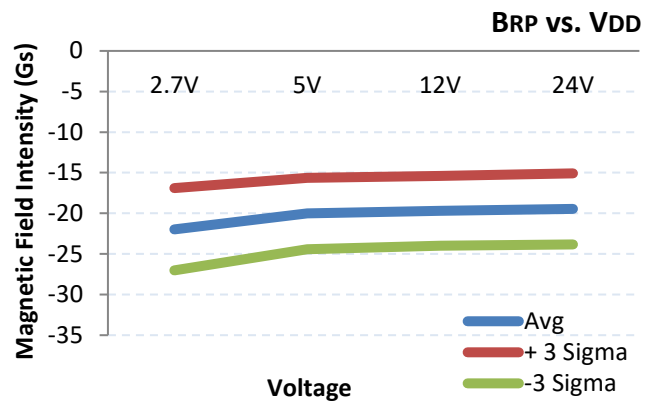
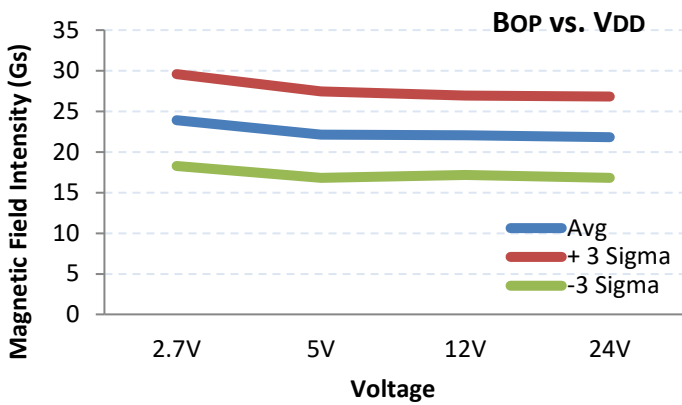


Figure.4 Magnetic Characteristics (BOP & BRP) vs.  $V_{DD}$  @ Temperature= $25^\circ C$

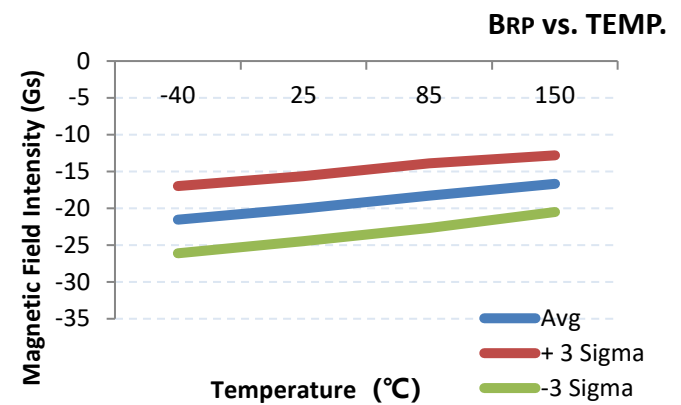
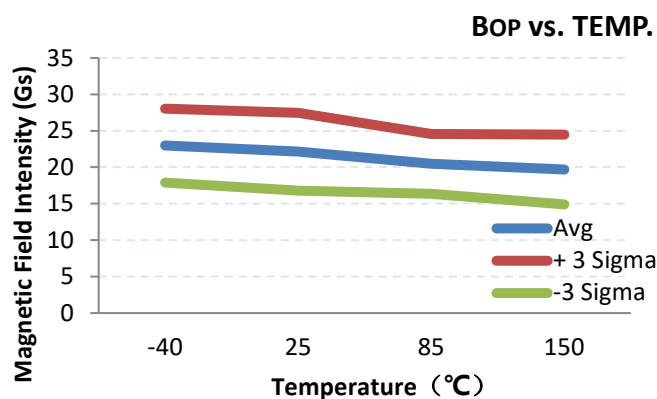
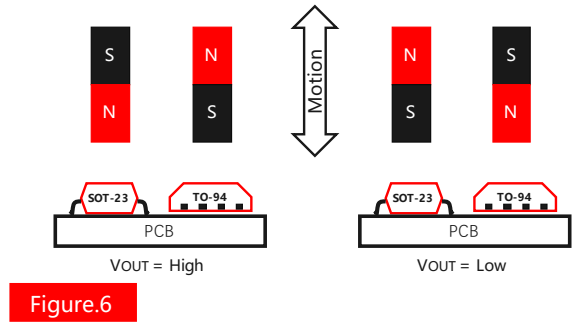


Figure.5 Magnetic Characteristics (BOP & BRP) vs. Temperature @  $V_{DD} = 5V$

### 8 Output Behavior vs. Magnetic Pole (SP1 + SP2 Mode)

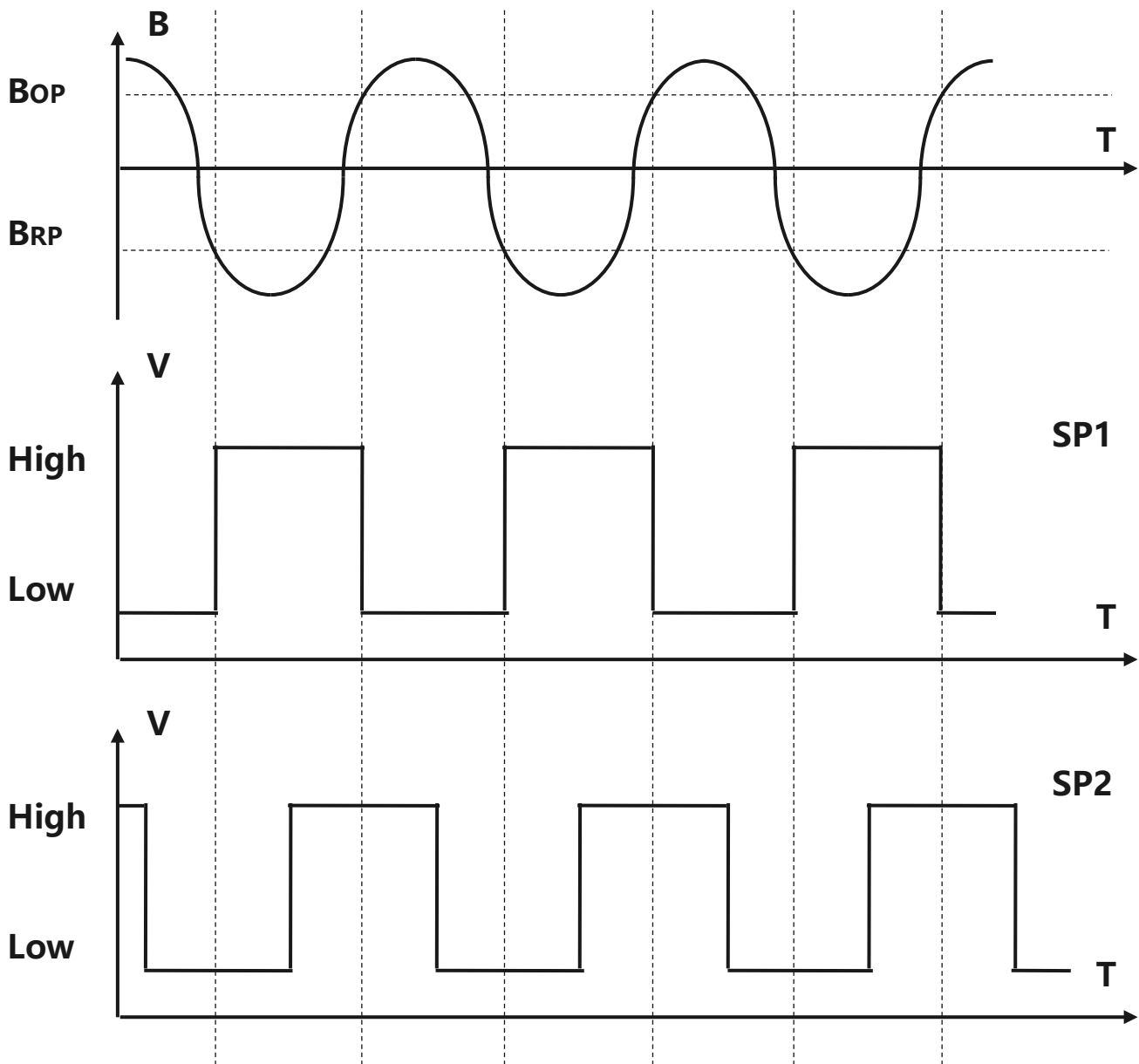
At  $T_A = -40 \sim 150 \text{ }^\circ\text{C}$ ,  $V_{DD} = 2.7\text{V} \sim 24\text{V}$  (unless otherwise specified)

Part No.	Parameter	Test Conditions	SP Output State
SOT-23 Series	South Pole	$B > B_{OP}$	Low
	North Pole	$B < B_{RP}$	High
TO-94 Series	North Pole	$B > B_{OP}$	Low
	South Pole	$B < B_{RP}$	High



#### 8.1 Typical Output Waveform (SP1 + SP2 Mode)

MT890XAT-SS as example



Note:  
The phase error between Speed 1 & Speed 2 depends on the environment of the application

Figure.7

### 9 Output Behavior vs. Magnetic Pole (SP1 + DIR Mode)

At  $T_A = -40 \sim 150 \text{ }^\circ\text{C}$ ,  $V_{DD} = 2.7\text{V} \sim 24\text{V}$  (unless otherwise specified), MT890XAT-SD as example

Parameter	Test Conditions	H1	H2	SP Output State
CCW	nX	N	S	Low
	n(X+1)	N	N	
	n(X+2)	S	N	
	n(X+3)	S	S	
	n(X+4) $\equiv$ nX	N	S	

Parameter	Test Conditions	H1	H2	SP Output State
CW	nX	N	S	High
	n(X+1)	S	S	
	n(X+2)	S	N	
	n(X+3)	N	N	
	n(X+4) $\equiv$ nX	N	S	

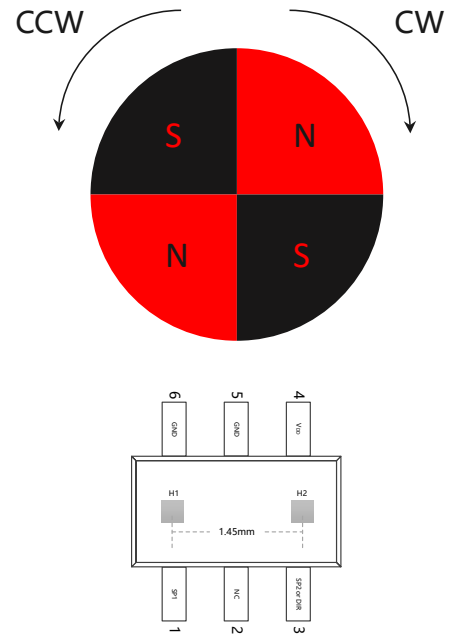
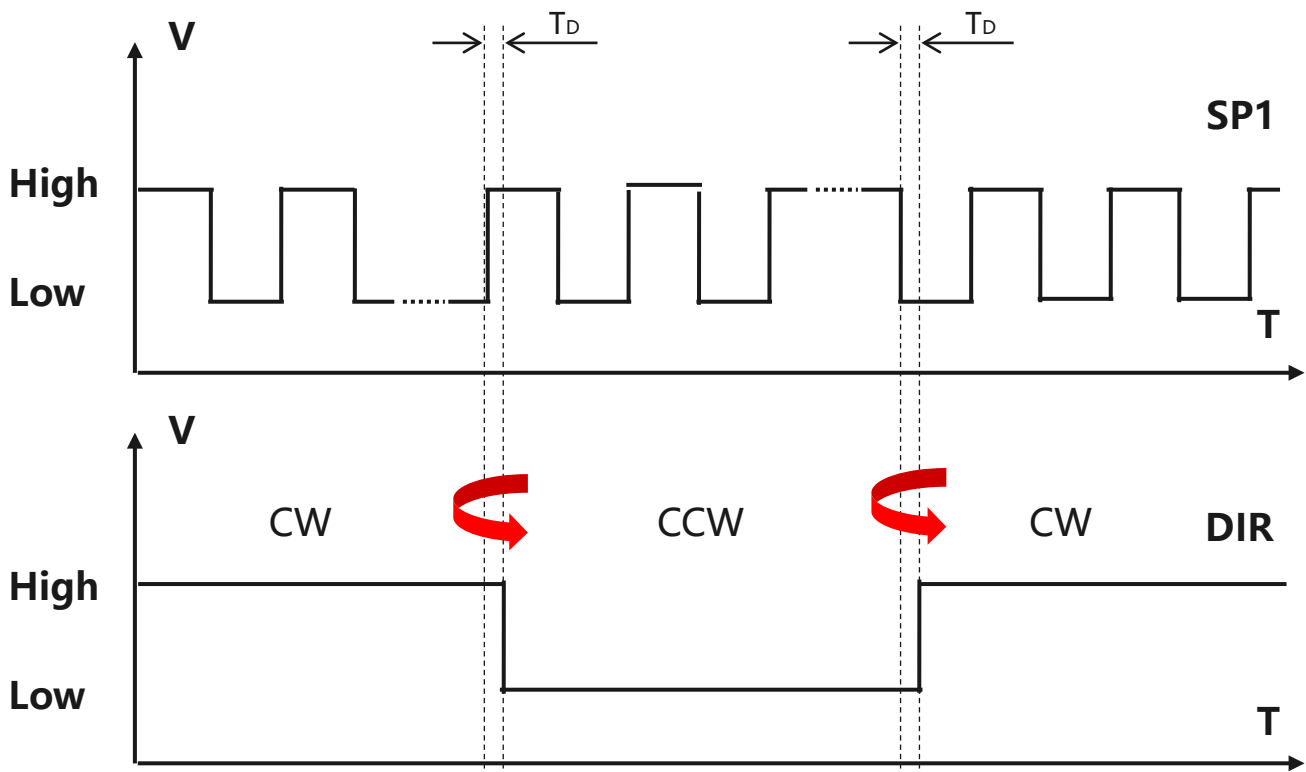


Figure.8

#### 9.1 MT8901-SD Typical Output Waveform (SP1 + DIR Mode)

MT8901AT-SD as example

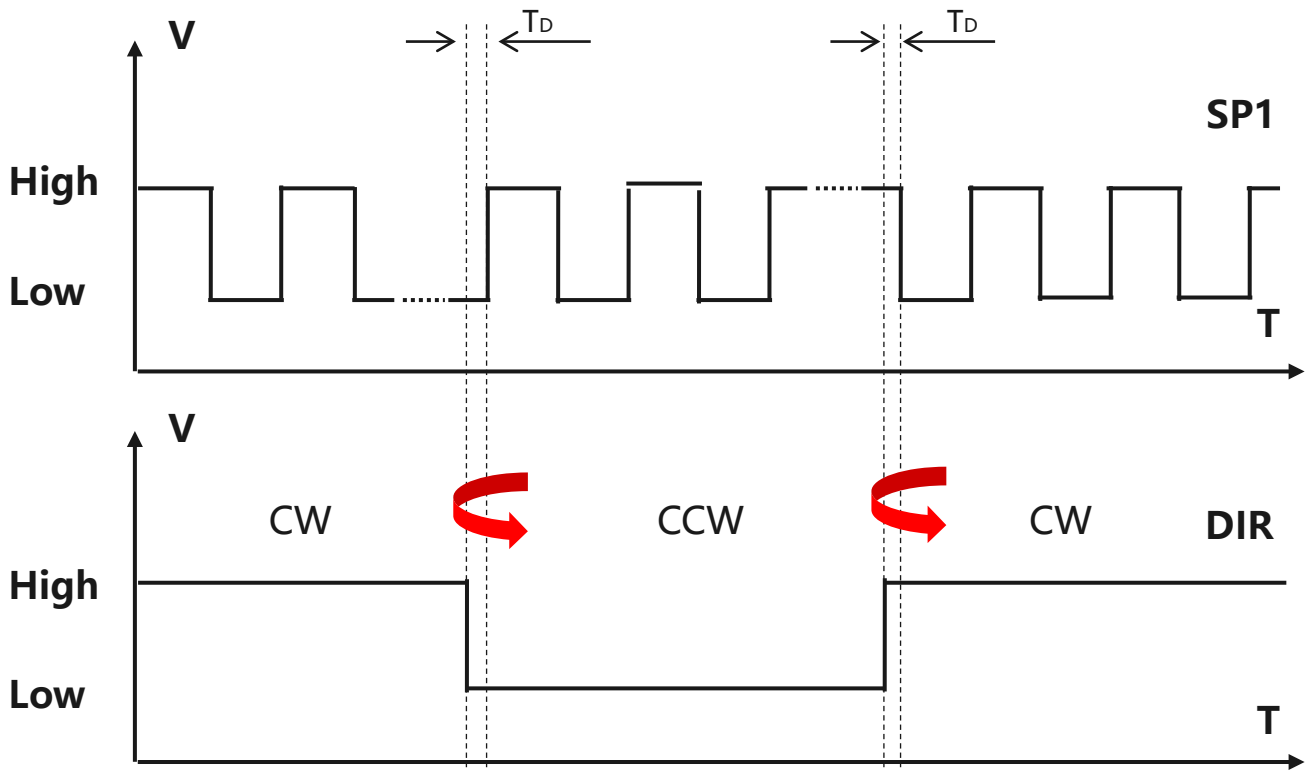


Note:  
The DIR phase of MT8901-SD lags the SP1 phase by typical 1.2 $\mu$ s

Figure.9

### 9.2 MT8902-SD Typical Output Waveform (SP1 + DIR Mode)

MT8902AT-SD as example



Note:  
The DIR phase of MT8902-SD leads the SP1 phase by typical  $1.2\mu\text{s}$

Figure.10

### 10 Typical Application Circuit

MT890XAT as example

Note: Recommended value for  $R_{L1}$  &  $R_{L2}$  is 5KOhms to 20KOhms

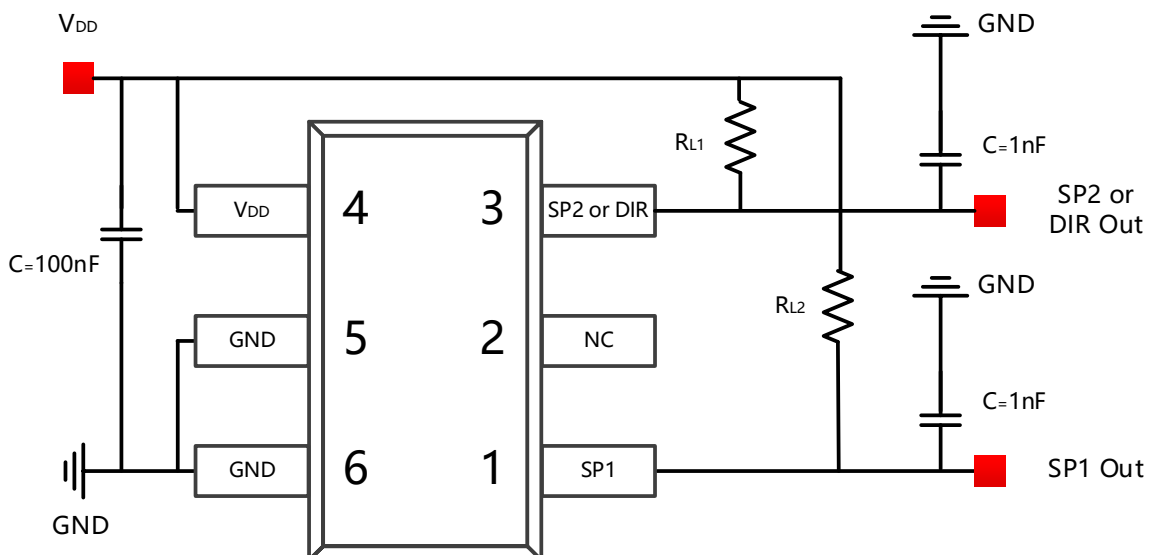


Figure.11 Typical Application Circuit

## 11 Self-diagnosis

The MT890X family offers self-diagnosis function during the sensor power-on. This allows the user to check the functionality of the whole signal path in response to BOP and BRP, as well as the wire connections of the sensor IC.

In order to activate the self-diagnosis function, user are advised to connect their system as shown in Figure.7, in which a host is required to control the VDD and SP1 port of the sensor. Then user should follow the following two steps:

Firstly the host has to power off the sensor and the host I/O pull the sensor SP1 output (VOUT1) low.

Then the host powers on the sensor, and the host I/O has to release the VOUT1 afterwards. Referring to the self-diagnosis timing diagram in Figure.8, there is a minimum time interval between  $t_{sup}$  (the moment when  $V_{SUP}$  has reached 90% of its final value) and  $t_{rls}$  (the moment when host I/O releases).

If any one of the 2 criteria above is violated, the sensor might skip the self-diagnosis phase and enter the normal operation mode.

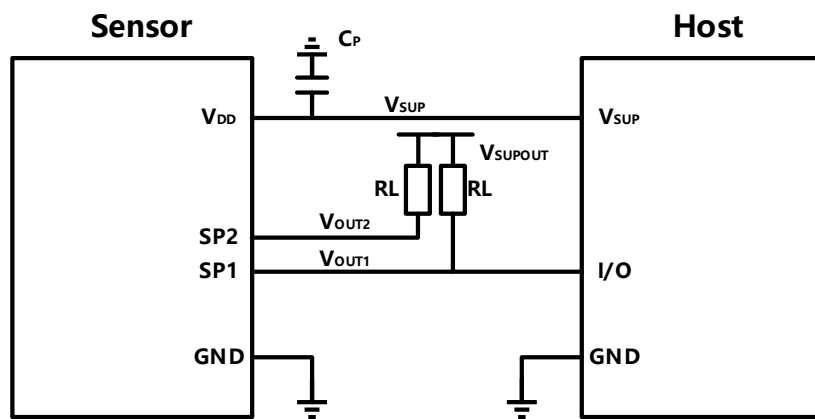


Figure.12 Sensor-Host connection diagram for self-diagnosis function

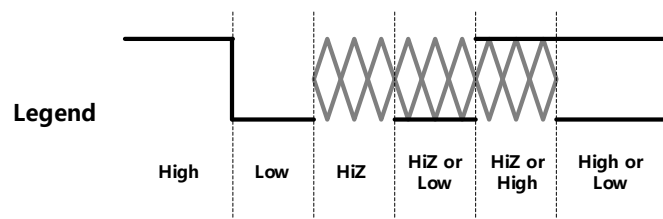
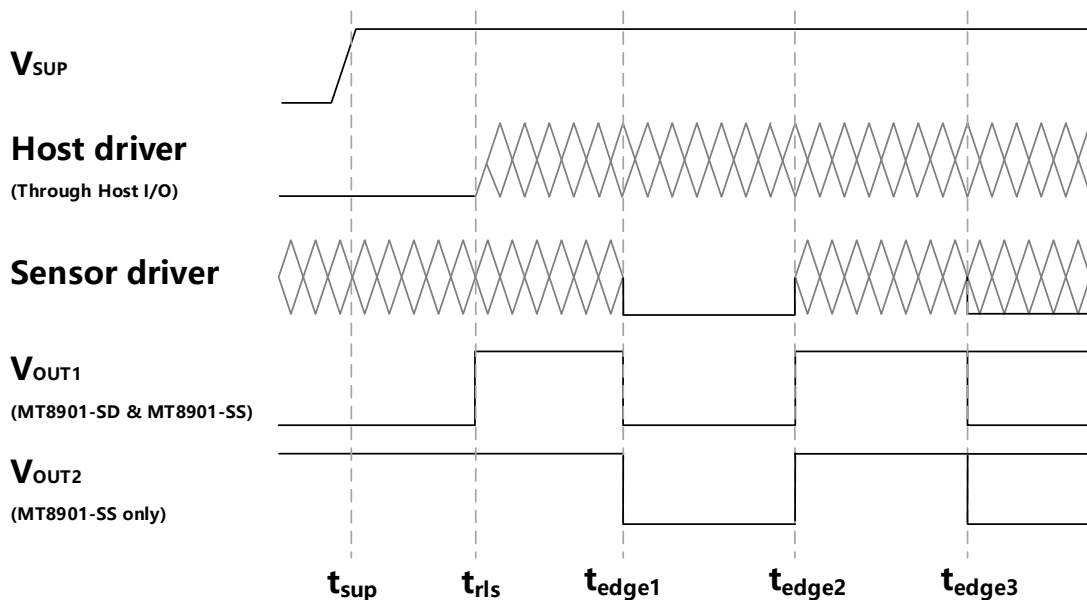


Figure.13 Self-diagnosis timing diagram

## 11 Self-diagnosis (Continued)

For MT8901-SD, the self-diagnosis function is only available for SP1. If the self-diagnosis function is activated, firstly the VOUT1 will be pulled high by RL since host I/O has released. Then the sensor will generate a first dummy signal that drives the SP1 output low, which simulates an BOP. The falling edge ( $t_{edge1}$ ) of VOUT1 will be captured by the host. Afterwards the sensor generates a second dummy signal of the opposite polarity that drives the SP1 output high (by RL), which simulates an BRP. The rising edge ( $t_{edge2}$ ) of VOUT1 is also captured by the host. Now the self-diagnosis phase has ended and then the sensor will enter its normal operation mode, sending the first real data to VOUT1 at  $t_{edge3}$ .

For MT8901-SS, the self-diagnosis function is available for both SP1 and SP2. The waveform of VOUT1 is same as MT8901-SD. VOUT2 is initially pulled up by the RL (not controlled by the host). Since  $t_{edge1}$ , VOUT2 waveform will be the same as VOUT1, until  $t_{edge3}$ , when the first real data of SP2 is sent to VOUT2.

The two captured edges ( $t_{edge1}$  and  $t_{edge2}$ ) should fall in a certain time window, specified in the table "Spec for self-diagnosis". This could be a criterion for host to determine whether or not the self-diagnosis has succeeded.

### Spec for self-diagnosis

Symbol	Parameters	Min	Typ	Max	Unit
$t_{rls}$	Host I/O release time	$t_{sup}+20^{(1)(2)}$	-	-	us
$t_{edge1}$	First falling edge of V <sub>OUT</sub> during self-diagnosis	$t_{rls}+5$	$t_{rls}+10$	$t_{rls}+15$	us
$t_{edge2}$	First rising edge of V <sub>OUT</sub> during self-diagnosis	$t_{edge1}+5$	$t_{edge1}+10$	$t_{edge1}+15$	us
$t_{edge3}$	First data available during normal operation	$t_{rls}+15$	$t_{rls}+30$	$T_{rls}+45$	us
$B_{detmax}$	Maximum external field allowed during self-diagnosis	-	5000	-	Gauss

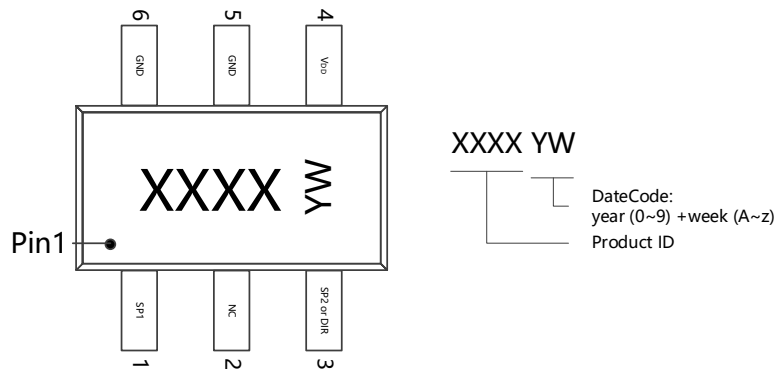
Notes:

(1)  $t_{sup}$  is the time when sensor V<sub>DD</sub> has reached 90% of its final value. V<sub>DD</sub>=V<sub>SUP</sub>.

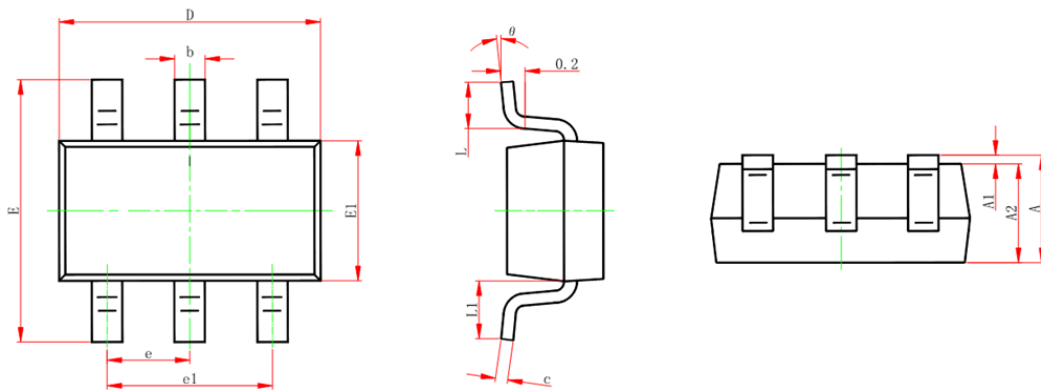
(2) Power-on of V<sub>DD</sub> has to be faster than 5V/us.

## 12 Package Material Information (For Reference Only – Not for Tooling Use)

### 12.1 SOT-23-6L Package Information



**Figure.14** SOT-23-6L Chip Marking Spec

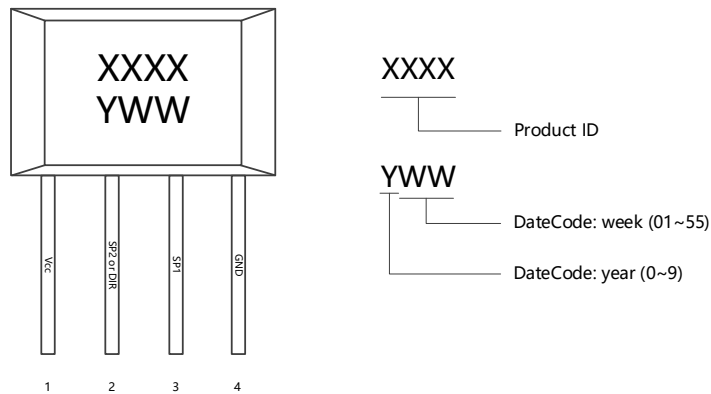


**Figure.15** SOT-23-6L Package Drawing

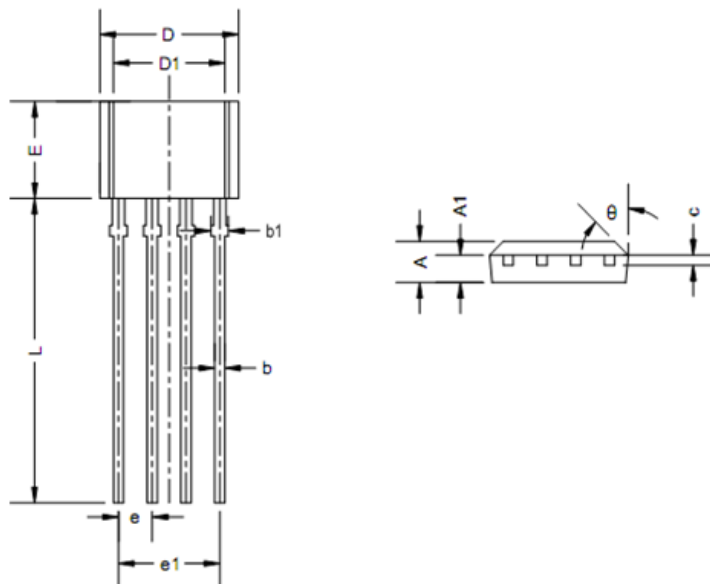
Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
L1	0.600 TYP		0.024 TYP	
θ	0 °	8 °	0 °	8 °

## 12 Package Material Information (For Reference Only – Not for Tooling Use)

### 12.2 Flat TO-94 Package Information



**Figure.16** Flat TO-94 Chip Marking Spec



**Figure.17** Flat TO-94 Package Drawing

Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	1.400	1.800	0.055	0.071
A1	0.700	0.900	0.028	0.035
b	0.360	0.500	0.014	0.020
b1	0.380	0.550	0.015	0.022
c	0.360	0.510	0.014	0.020
D	4.980	5.280	0.196	0.208
D1	3.780	4.080	0.149	0.161
E	3.450	3.750	0.136	0.148
e	1.270 TYP		0.050 TYP	
e1	3.710	3.910	0.146	0.154
L	14.900	15.300	0.587	0.602
θ	45 °		45 °	

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